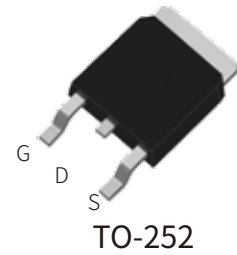


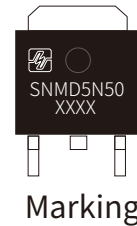
## FEATURES

- | Low Gate Charge
- | Low ON Resistance
- | Improved dv/dt Capability
- | 100% Avalanche Tested



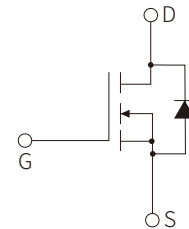
## APPLICATION

- | Switching Mode Power Supplies (SMPS)
- | Uninterruptible Power Supply (UPS)
- | Power Factor Correction (PFC) (PFC)
- | Charger



## APPROVALS

RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003



Schematic Symbol

## ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub>=25°C)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (V <sub>GS</sub> =0V)	V <sub>DS</sub>	500	V
Continuous Drain Current <sup>1)</sup>	I <sub>D</sub>	T <sub>c</sub> =25°C	5 A
		T <sub>c</sub> =100°C	3 A
Drain current pulsed <sup>2)</sup>	I <sub>D,pulse</sub>	20	A
Gate-Source Voltage	V <sub>GS</sub>	±30	V
Single pulsed Avalanche Energy <sup>3)</sup>	E <sub>AS</sub>	180	mJ
MOSFET dv/dt Ruggedness, V <sub>DS</sub> = 0...480V	dv/dt	5	V/ns
Total power dissipation (@T <sub>c</sub> =25°C)	P <sub>D</sub>	48.3	W
Continuous Diode Forward Current	I <sub>S</sub>	5	A
Diode Pulsed Current <sup>2)</sup>	I <sub>S,pulse</sub>	20	A
Operating Junction Temperature & Storage Temperature	T <sub>STG</sub> , T <sub>J</sub>	-55 to +150	°C
Thermal Resistance, Junction-to-Case	R <sub>thJC</sub>	2.59	°C/W
Thermal Resistance, Junction-to-Ambient	R <sub>thJA</sub>	62	°C/W

### Notes

1. Limited by maximum junction temperature.
2. Repetitive Rating: Pulse width limited by maximum junction temperature.
3. L=10mH, I<sub>D</sub>=5A, Start T<sub>J</sub>=25°C

## ELECTRICAL CHARACTERISTICS (T<sub>A</sub>=25°C)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
<b>Static Characteristics</b>							
Drain-source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	500			V	
Zero Gate Voltage Drain current	I <sub>DSS</sub>	V <sub>DS</sub> =500V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C			1	μA	
		V <sub>DS</sub> =500V, V <sub>GS</sub> =0V, T <sub>J</sub> =150°C			100	μA	
Gate Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±30V			±100	nA	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2		4	V	
Drain-Source On-State-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =2.5A		1.2	1.5	Ω	
Gate Resistance	R <sub>G</sub>	f = 1.0MHz open drain		2.5		Ω	
<b>Dynamic Characteristics</b>							
Input capacitance	C <sub>ISS</sub>	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f=1MHz		488		pF	
Output capacitance	C <sub>OSS</sub>				60		pF
Reverse Transfer capacitance	C <sub>rss</sub>				7.2		pF
Turn-on Delay Time	td(on)	V <sub>DD</sub> =250V, I <sub>D</sub> =5A, R <sub>G</sub> =10Ω V <sub>GS</sub> =10V		14		ns	
Rising time	tf				18		ns
Turn-off Delay Time	td(off)				32		ns
Input capacitance	tf				11		ns
Total gate charge	Q <sub>g</sub>	V <sub>DD</sub> =400V, I <sub>D</sub> =5A, V <sub>GS</sub> =10V		16.5		nC	
Gate-source charge	Q <sub>gs</sub>				3.8		nC
Gate-drain charge	Q <sub>gd</sub>				5.6		nC
Gate Plateau Voltage	V <sub>Plateau</sub>				4.6		V
<b>Drain-Source Body Diode Characteristics</b>							
Diode forward voltage drop.	V <sub>SD</sub>	I <sub>SD</sub> =5A, V <sub>GS</sub> =0V, T <sub>J</sub> = 25°C			1.2	V	
Reverse recovery time	T <sub>rr</sub>	V <sub>R</sub> =400V, I <sub>F</sub> =5A, di <sub>F</sub> /dt=100A/us		328		ns	
Reverse recovery Charge	Q <sub>rr</sub>				1.6		uC

# CHARACTERISTIC CURVES

Fig.1 Transient Thermal Impedance

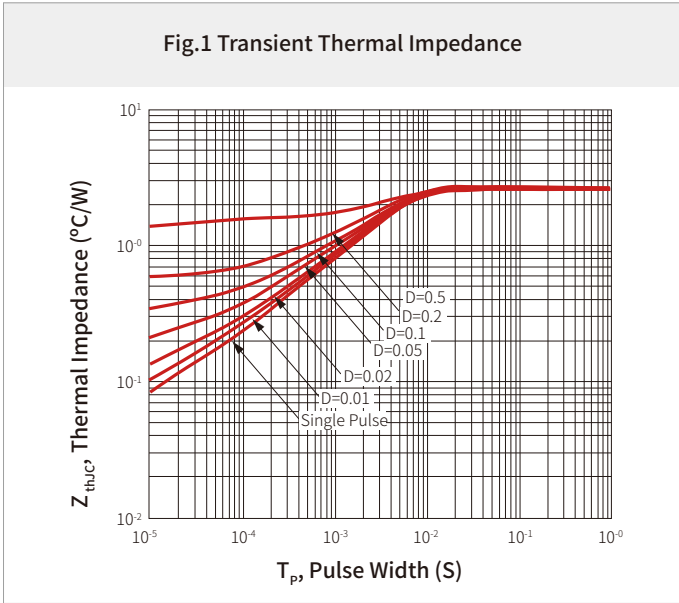


Fig.2 Transient Thermal Impedance

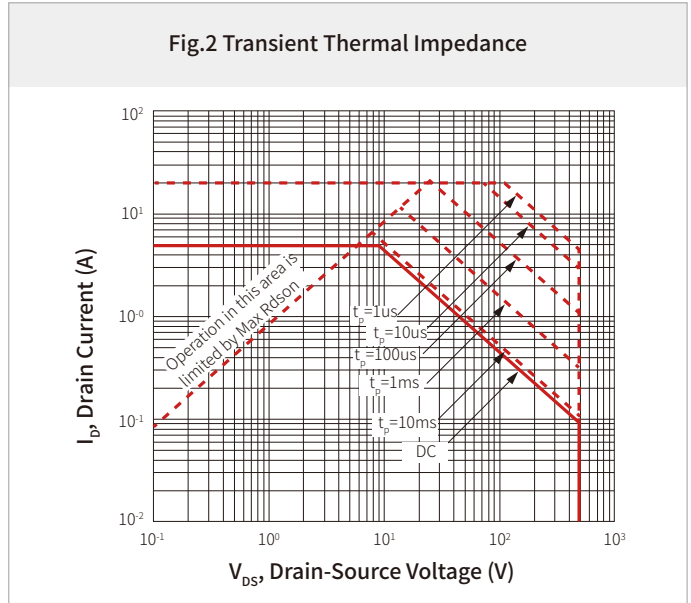


Fig.3 Transfer Characteristics

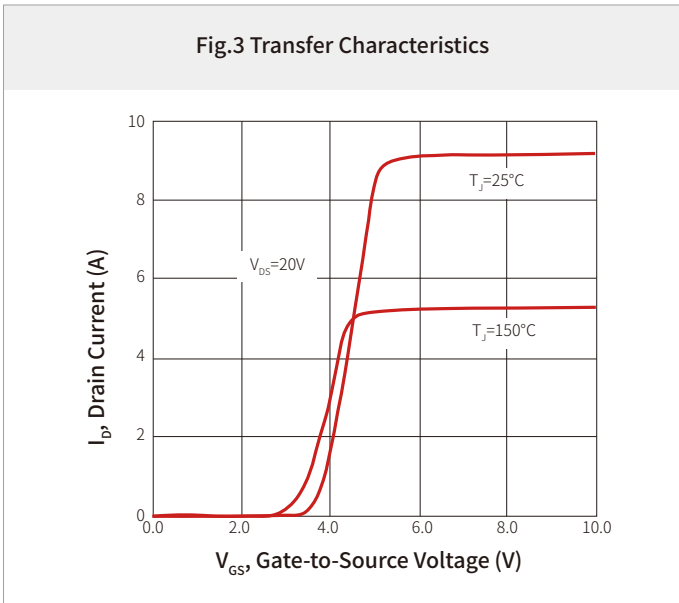


Fig.4 Capacitance Characteristics

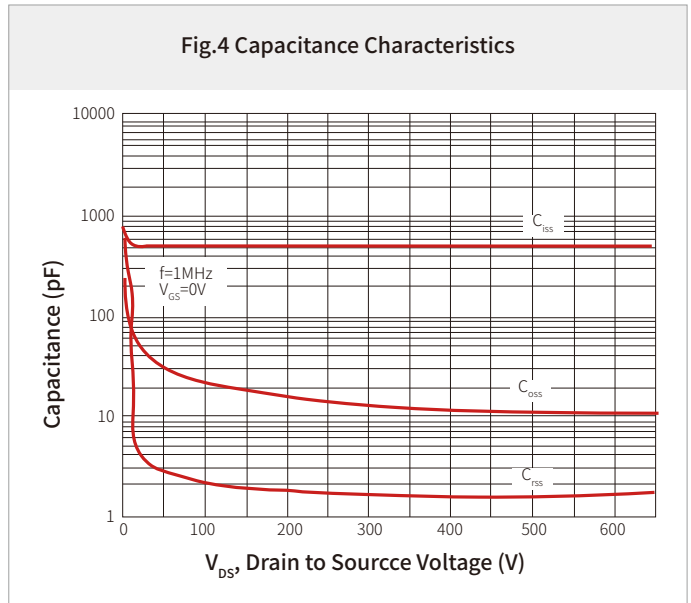


Fig.5 On-Resistance vs Drain Current

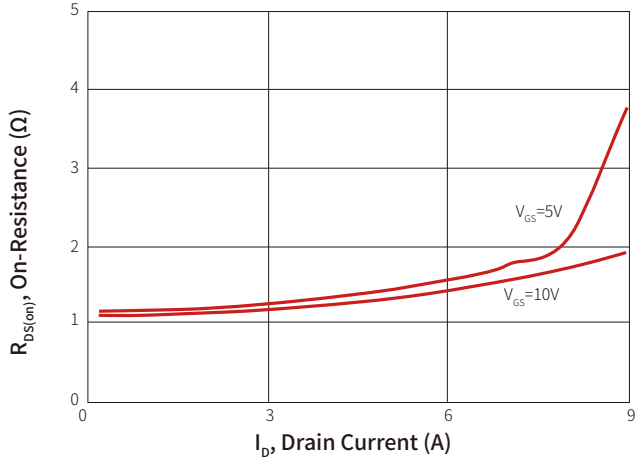


Fig. 6 Capacitance

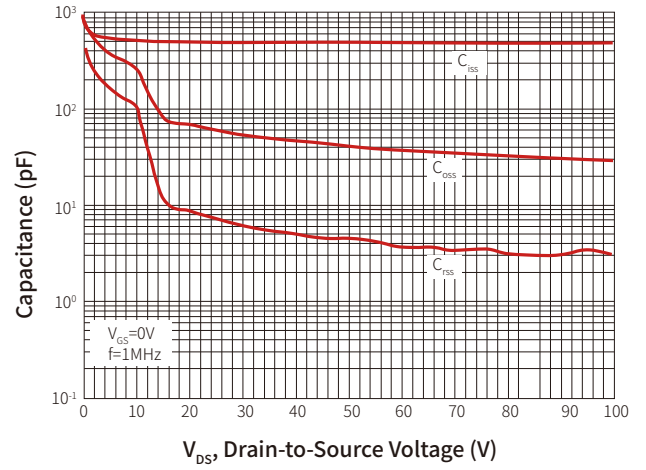


Fig.7 Gate Charge

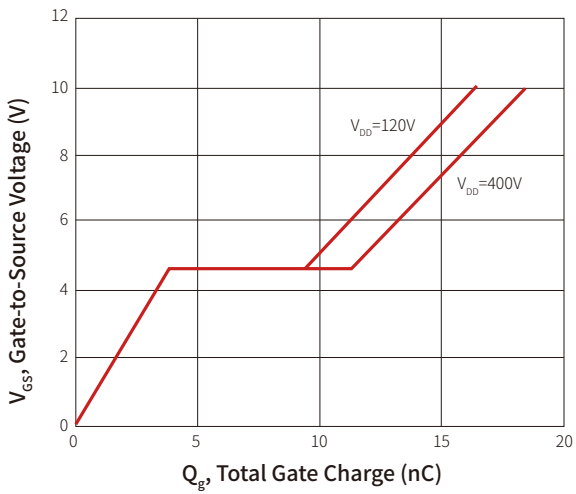
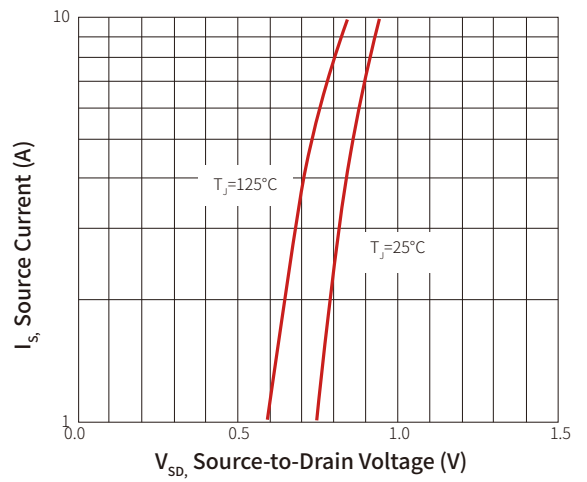
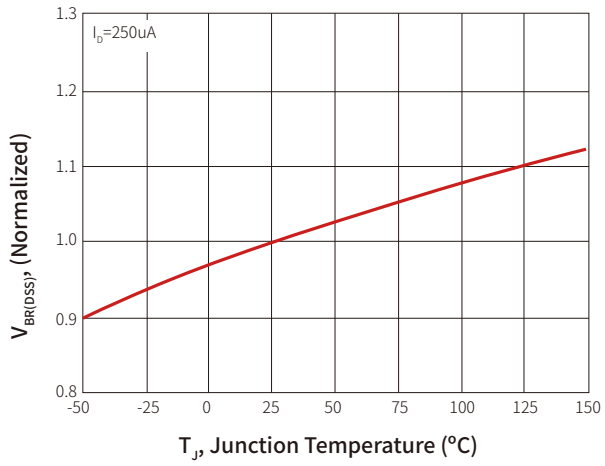


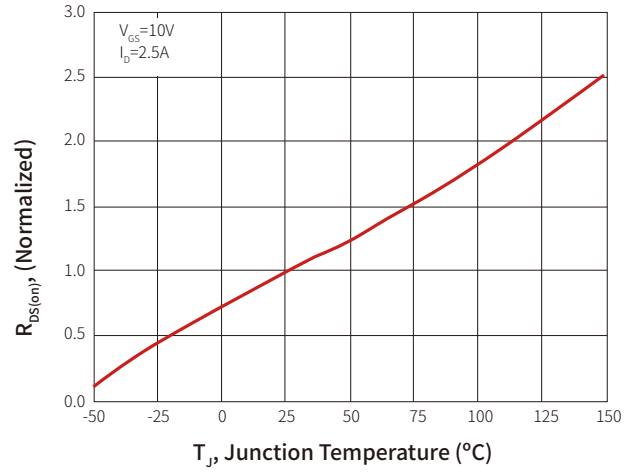
Fig.8 Body Diode Forward Voltage



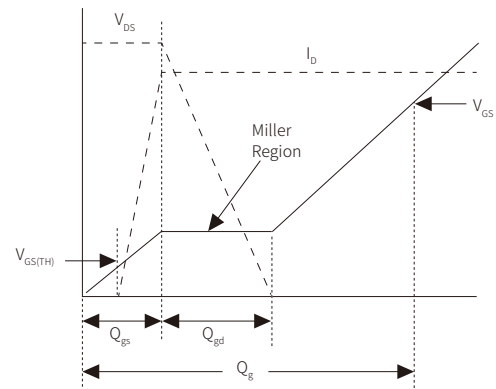
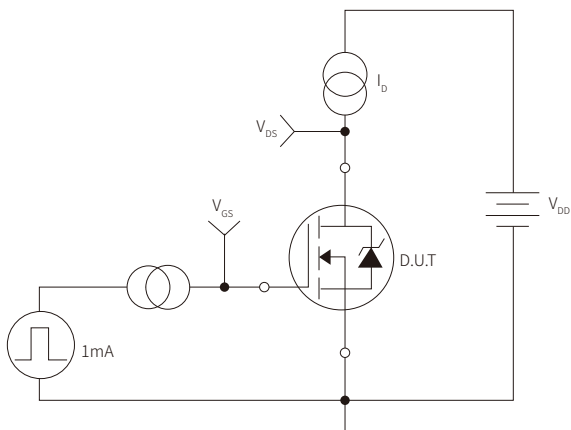
**Fig.9 Breakdown Voltage vs Junction Temperature**



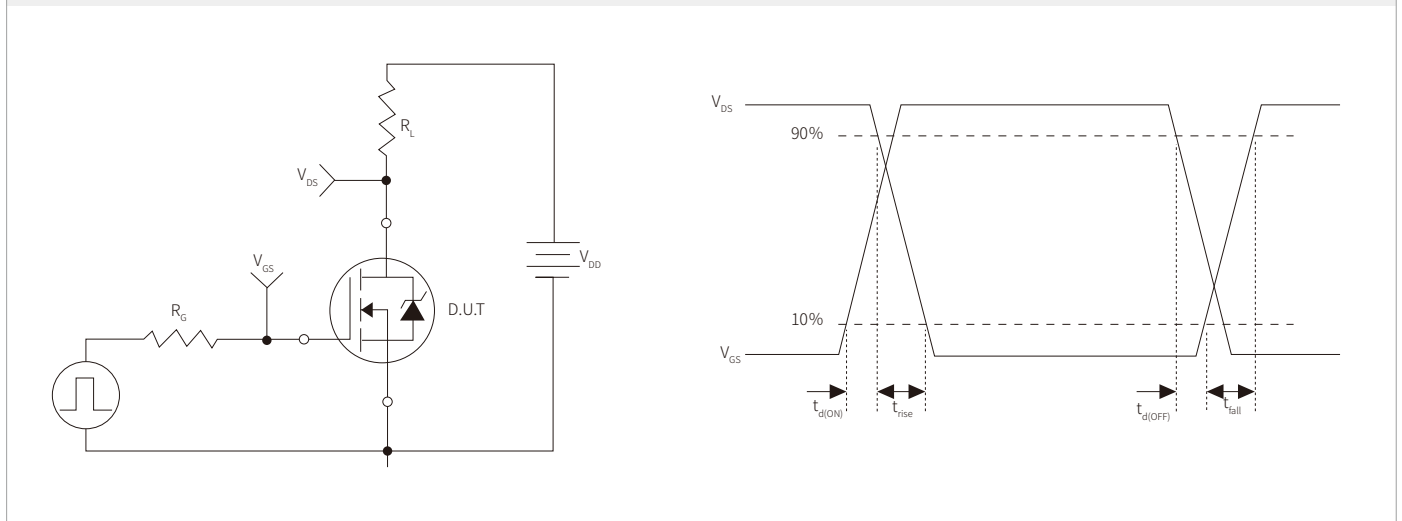
**Fig. 10 On-Resistance vs Temperature**



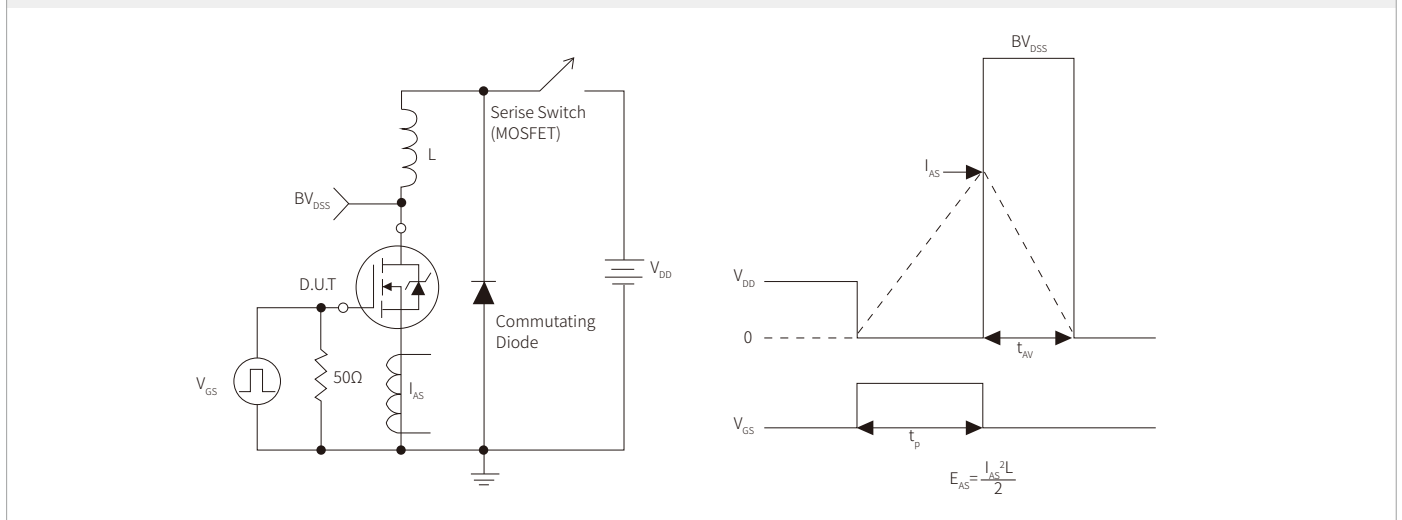
**Fig.11 Gate Charge Test Circuit and Waveform**



**Fig.12 Resistive Switching Test Circuit and Waveform**

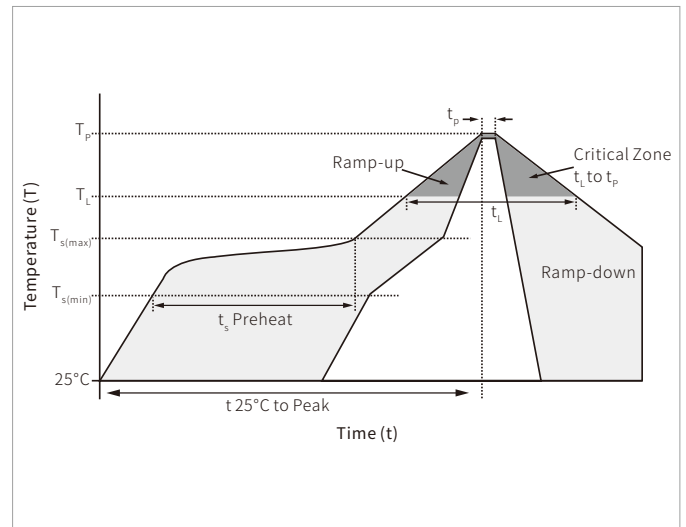


**Fig.13 Unclamped Inductive Switching Test Circuit and Waveform**

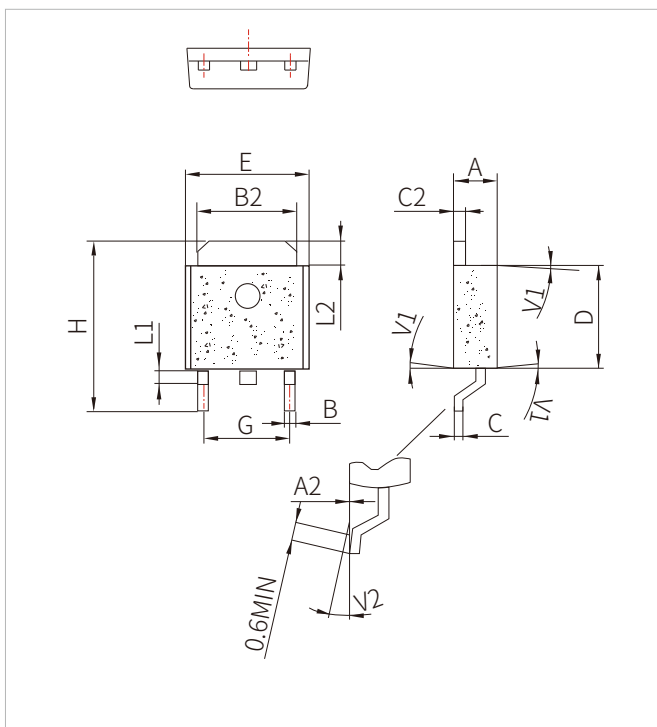


## SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ( $T_{s(min)}$ )	150°C
	Temperature Max ( $T_{s(max)}$ )	200°C
	Time (min to max) ( $t_s$ )	60 – 180 secs
Average ramp up rate (Liquidus Temp ( $T_L$ ) to peak)		3°C/second max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/second max
Reflow	Temperature ( $T_L$ ) (Liquidus)	217°C
	Time (min to max) ( $t_L$ )	60 – 150 seconds
Peak Temperature ( $T_p$ )		260°C
Time within 5°C of actual peak Temperature ( $t_p$ )		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature ( $T_p$ )		8 minutes max.
Do not exceed		260°C



## TO-252 PACKAGE MECHANICAL DATA



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0.03		0.23	0.001		0.009
B	0.55		0.65	0.022		0.026
B2	5.10		5.40	0.200		0.213
C	0.45		0.62	0.018		0.024
C2	0.48		0.62	0.019		0.024
D	6.00		6.20	0.236		0.244
E	6.40		6.80	0.252		0.268
G	4.40		4.70	0.173	0.1	0.185
H	9.35		10.7	0.368		0.421
L1	1.30		1.70	0.051	0.143	0.067
L2	1.37		1.50	0.054		0.059
V1		4°			0.130	
V2	0°		8°	0°		8°

## ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
SNMD5N50	TO-252	5000PCS	13"



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